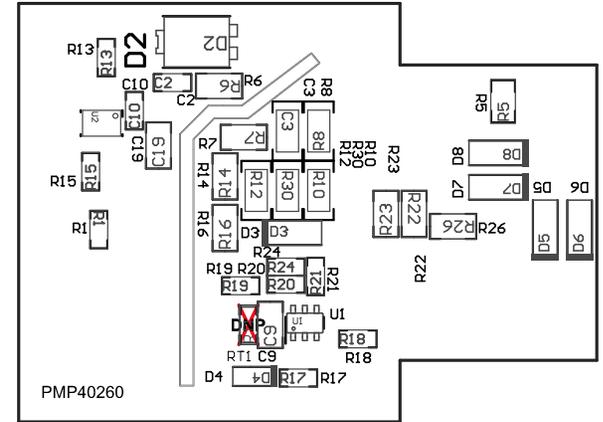


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP40260	REV: A	SVN REV: Not In VersionControl
Top Overlay	TID #: PMP40260		
PLOT NAME = Top Assembly Drawing	GENERATED : 11/8/2017	11:25:08 AM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP40260	REV: A	SUN REV: Not In VersionControl
	TID #: PMP40260	Bottom Overlay	
PLOT NAME = Bottom Assembly Drawing	GENERATED : 11/8/2017	11:25:11 AM	TEXAS INSTRUMENTS

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